Preliminary Product Information Sheet

EPO-TEK® 330-LH (*formerly 114-74-2*)

Note: These are typical properties to be used as a guide only, not a specification. Data below is not guaranteed. Different batches, conditions and applications yield differing results.

Date: September 2017
Rev: III
No. of Components: Two
Mix Ratio by Weight: 10 : 1
Specific Gravity: Part A: 1.13 Part B: 1.01
Pot Life: 6 Hours
Shelf Life- Bulk: One year at room temperature

Recommended Cure: 150°C / 1 Hour

Minimum Alternative Cure(s):
May not achieve performance properties listed below
150°C / 1 Minute
120°C / 5 Minutes
100°C / 10 Minutes
80°C / 30 Minutes

NOTES:

- Container(s) should be kept closed when not in use.
- Filled systems should be stirred thoroughly before mixing and prior to use.
- Performance properties (rheology, conductivity, others) of the product may vary from those stated on the data sheet when bi-pak/syringe packaging or post-processing of any kind is performed. Epoxy's warranties shall not apply to any products that have been reprocessed or repackaged from Epoxy's delivered status/container into any other containers of any kind, including but not limited to syringes, bi-paks, cartridges, pouches, tubes, capsules, films or other packages.
- Syringe packaging will impact initial viscosity and effective pot life, potentially beyond stated parameters.
- If product crystalizes in storage, place container in warm oven until crystallization disappears. Please refer to Tech Tip #7 on website.
- *TOTAL MASS SHOULD NOT EXCEED 25 GRAMS*

Product Description: A low halogen version of EPO-TEK® 330. It is a two component, high-temperature grade, electrically and thermally insulating epoxy for semiconductor, electronics, and fiber optic applications.

MATERIAL CHARACTERISTICS*:

PHYSICAL PROPERTIES:	**Cure condition:** 150°C / 1 Hour	
Color (before cure):	Part A: Clear/Colorless Part B: Amber	
Consistency:	Pourable liquid	
Viscosity (23°C) @ 100 rpm:	310	cPs
Thixotropic Index:	N/A	
Glass Transition Temp:	87	°C (Dynamic Cure: 20-200°C/ISO 25 Min; Ramp -10-200°C @20°C/Min)
Coefficient of Thermal Expansion (CTE):		
Below Tg:	66	x 10^{-6} in/in°C
Above Tg:	145	x 10^{-6} in/in°C
Shore D Hardness:	85	
Die Shear @ 23°C:	21	Kg
Degradation Temp:	370	°C
Weight Loss:		
@ 200°C:	0.81	%
@ 250°C:	1.23	%
@ 300°C:	2.18	%
Suggested Operating Temperature:	< 300	°C (Intermittent)
Storage Modulus:	279,324	psi
Particle Size:	N/A	

OPTICAL PROPERTIES @ 23°C:		
Spectral Transmission:	≥ 97% @ 740-1880	nm
Refractive Index:	1.5298 @ 589	nm

The data above is INITIAL only - it may be changed at any time, for any reason without notice to anyone. It is provided only as a guide for evaluation/consideration.

* These material characteristics are typical properties that are based on a limited number of samples/batches. All properties are based on the cure indicated above. Some properties may vary as manufactured quantities are scaled up to commercialized production levels.

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